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REVISIONS

REV.	DESCRIPTION	DATE	APPROVED
A	RELEASE/CHANGE PER ECO-R242091	SEE AGILE	SEE AGILE

NOTES: UNLESS OTHERWISE SPECIFIED.

1.

APPLICABLE STANDARDS/SPECIFICATIONS:
ASME Y14.3-2012, ORTHOGRAPHIC AND PICTORIAL VIEWS.
ASME Y14.5-2009, DIMENSIONS AND TOLERANCES.
ASME Y14.38-2013, ABBREVIATIONS AND ACRONYMS.

ALL SPECIFICATIONS REFERENCED SHALL BE OF THE LATEST REVISIONS.

2.

ALL DIMENSIONS IN MM.

3.

FABRICATE IN ACCORDANCE WITH IPC-6012 TYPE 3 PER IPC-6011 CLASS 3 MINIMUM DIELECTRIC ACCEPTABLE TO BE 0.050 (.002).

4.

MATERIAL: COPPER CLAD LAMINATES ISOLA 370HR (OR EQUIVALENT), ROHS COMPLIANT. U.L. DESIGNATION: ANSI GRADE FR-4, PER IPC 4101. COPPER WEIGHT SHALL BE 1/2 OZ. PLATED TO 1 OZ. ON EXTERNAL LAYERS AND 1 OZ. ON INTERNAL LAYERS. OVERALL BOARD THICKNESS TO BE 1.6MM ± 10%..BOARD PROFILE TOLERANCE TO BE ± 0.2MM. COPPER PLATE ON WALLS OF HOLES SHALL BE .001 AVERAGE, .0008 ABSOLUTE MINIMUM. ENIG FINISH AND FOLLOW IPC-4552 TO BUILD.

5.

GERBER DATA MUST BE VERIFIED AGAINST THE IPC-356A NETLIST BEFORE FABRICATION.

6.

MINIMUM CONDUCTOR WIDTHS OF 0.100 (0.004) AND SPACINGS OF 0.100 (0.004) SHALL BE HELD WITHIN +/- 20% OF ORIGINAL DATA.

7.

ALL SMD PAD PLATING TO BE FLAT TO A MAX. OF 0.080 (0.003) ABOVE BOARD SURFACE.

8.

USE GREEN LIQUID PHOTO IMAGEABLE SOLDER MASK CONFORMING TO IPC-SM-840, CLASS H. BOARD TO HAVE SOLDER MASK OVER BARE COPPER ON BOTH SIDES. NO SOLDERMASK TO PAD PERMISSIBLE, EXCEPT VIAS.

9.

ALL EXPOSED CONDUCTIVE SURFACES TO BE IMMERSION NICKEL/GOLD PLATING USING 100-400 MICROINCHES NICKEL AND 2-5 MICROINCHES GOLD.

10.

WARP OR TWIST OF BOARD SHALL NOT EXCEED 0.75%.

11.

SILKSCREEN BOTH SIDES USING WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE EPOXY INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PADS.

12.

REMOVE ALL BURRS AND BREAK SHARP EDGES 0.400 (0.015) MAX.

13.

FINISHED BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO, DATE CODE AND LOT IDENTIFICATION SHALL BE LOCATED ON THE TOP SIDE OF THE BOARD IN ETCH. SILKSCREEN ACCEPTABLE.

14.

ALL BOARDS TO BE 100% ELECTRICALLY TESTED USING AN IPC-356A NETLIST. ALL NETS TO BE CHECKED FOR CONTINUITY AND SHORTS.

15.

TEST DATA AND CERTIFICATE OF COMPLIANCE TO BE SUPPLIED WITH EACH BATCH OF BOARDS.

16.

MINIMUM ANNULAR RING IS .001. TANGENCY IS PERMITTED ON .036 AND .009 DRILL HOLES.

17.

LAYER REGISTRATION TO BE <0.004".

18.

ENSURE ALL UPDATES TO THIS DRAWING ARE INCORPORATED INTO ARTWORK FILES UNDER COVIDIEN P/N 10107738 AS NECESSARY.

19.

PART/COMPONENT TO BE RoHS COMPLIANT.

SIZE

QTY

SYM

PLATED

TOL

0.4	183	+	YES	+/-0.127
1	19	×	YES	+/-0.127
0.8	4	□	YES	+/-0.127
1.3	16	◇	YES	+/-0.127
3	2	⊠	YES	+/-0.127
3.18	1	⊠	NO	+/-0.050
1.7	2	+ ^A	YES	+/-0.127

LAYUP DETAIL
2 LAYER

1.6±.16

SILKSCREEN (TOP SIDE)

SOLDERMASK (TOP SIDE)

LAYER 1 (TOP SIDE)

ITEQ IT-140

LAYER 2 (BOTTOM SIDE)

SOLDERMASK (BOTTOM SIDE)

SILKSCREEN (BOTTOM SIDE)

34.0mm

28.0mm

92.0mm

210.0mm

VIEWS SHOWN ARE FOR REFERENCE ONLY. SOURCE INFORMATION CONTAINED IN GERBER FILES UNDER P/N 10107738 LATEST REVISION

GENERAL
DIMENSIONAL TOLERANCES

DEC.	DEC.	DEC.	DEC.
X +/-	.x +/-	.xx +/-	.xxx +/-
-	.2	-	-
DEC.	HOLES	FRAC.	ANG.
.xxxx +/-	+/-	+/-	+/-
-	-	-	-

SCALE: 1:1

DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

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TITLE:

POWERPACK2 BARE BOARD

COVIDIEN

6135 Gunbarrel Avenue
Boulder, CO 80301

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SIZE

A3

FILENAME:

10106054.SLDDRW

DRAWING NO.:

10106054

REV

A

DRAWN:

DATE:

28FEB2013

CHECKED:

SEE AGILE

DATE:

SEE AGILE

APPROVED:

SEE AGILE

DATE:

SEE AGILE

SHEET:

1 OF 1

TEMPLATE 10083151 REV C

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